

Contamination control

Building on fifty years of experience in supporting semiconductor development and manufacturing, Eurofins EAG offers a wide range of contamination control services. Through the application of a large number of analytical technologies, we help our customers with contamination control issues as diverse as analysis of supply gases at the ppq levels to sub-monolayer analysis of wafer surfaces. Our services include research and development of new techniques, solving contamination problems on-site and providing routine analyses for existing products and processes.

Leveraging Science and Engineering to Accelerate Innovation

When it comes to understanding the physical structure, chemical properties



and performance of advanced materials and integrated circuitry, no other scientific services company offers the breadth of experience, diversity of analytical techniques or technical ingenuity of Eurofins EAG. We deliver multi-disciplinary, problem-solving expertise to help our customers accelerate innovation, ensure quality and safety, and protect intellectual property.

| Cleanroom | Application | Technique |
|---|--|--------------------------------------|
| Cleanroom air | Particle count and size | DPC, SEM |
| | Airborne molecular contamination | GC-FID/MS/AED, IC, ICP-MS, IMS |
| Supplies: gases | Total organic contamination (TOC) | TD-GC-FID/MS/AED |
| | Moisture | CRDS, NIR-TDLS, CMS |
| | Acids/base | IC |
| | CO/CO ₂ | NDIR |
| | Hydrogen/oxygen | MS, portable monitors |
| | Particle count and size | DPC, SEM |
| | Total organic carbon (TOC) | TOC-analyzer |
| Supplies: ultra-pure water | Anions and cations | IC, ICP-MS |
| | Particle count and size | LPC |
| | | |
| Equipment & Modules | | |
| Cleanliness validation of products & parts | Total organic contamination (TOC) | TD-GC-FID/MS |
| | Anions and cations | IC, ICP-MS |
| | Refractory components (S, Si, P, B containing) | GC-MS/AED |
| | Particle count and size | DPC, LPC, SEM |
| Outgassing qualifications of materials | Analysis of evolved gases | TD-GC-FID/MS/AED, TGA-MS, TPR-MS |
| | | 0514 |
| Trouble shooting | Particles, stains | SEM |
| | Organics | FT-IR, Raman |
| | Bulk Impurities | TOF-SIMS, LA-ICP-MS |
| | Surface contaminants | SEM, XPS, TOF-SIMS, RBS |
| Wafers & Devices | | |
| Wafers | Particles, stains | SEM, Auger, TEM, AFM |
| | Organics | FT-IR, Raman, XPS, TOF-SIMS |
| | Surface contaminants | SEM, XPS, TXRF, TOF-SIMS, VPD-ICP-MS |
| Devices | Particle etch residue | SEM, XPS, Auger, TEM, AFM |
| | Organics | FTIR, Raman, XPS, TOF-SIMS |
| | 0.901100 | |

